

NPN Silicon Germanium RF Transistor*

- High gain ultra low noise RF transistor for low current operation
- Ideal for low power consumption LNA design
- Provides outstanding performance for a wide range of wireless applications up to 10 GHz and more
- Outstanding noise figure F = 0.5 dB at 1.8 GHz
 Outstanding noise figure F = 0.8 dB at 6 GHz
- High maximum stable and available gain at only 7m. $G_{\rm ms} = 25$ dB at 1.8 GHz, $G_{\rm ma} = 18$ dB at 6 GHz
- 150 GHz f_T-Silicon Germanium technology
- Extremely small and flat leadless package, height 0.32 mm max.
- Pb-free (RoHS compliant) package 1)
- Qualified according AEC Q101
- * Short term description

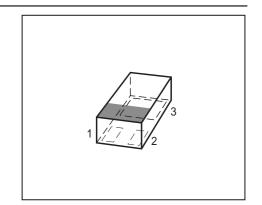




ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration			Package	
BFR705L3RH	R1	1=B	2=C	3=E	TSLP-3-9	

¹Pb-containing package may be available upon special request





Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$		V
$T_{A} > 0^{\circ}C$		4	
$T_{A} \leq 0^{\circ}C$		3.5	
Collector-emitter voltage	V _{CES}	13	
Collector-base voltage	V_{CBO}	13	
Emitter-base voltage	V _{EBO}	1.2	
Collector current	I _C	10	mA
Base current	I _B	1	
Total power dissipation ¹⁾ , T _S ≤ 123 °C	P _{tot}	40	mW
Junction temperature	T_{i}	150	°C
Ambient temperature	T_{A}	-65 150	
Storage temperature	T _{stg}	-65 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R _{thJS}	≤ 665	K/W

Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					•
Collector-emitter breakdown voltage	V _{(BR)CEO}	4	4.7	-	V
$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$, ,				
Collector-emitter cutoff current	I _{CES}	-	-	30	μA
$V_{CE} = 13 \text{ V}, \ V_{BE} = 0$					
Collector-base cutoff current	I _{CBO}	-	-	100	nA
$V_{CB} = 5 \text{ V}, I_{E} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	1	μA
$V_{\rm EB} = 0.5 \rm V, \ I_{\rm C} = 0$					
DC current gain	h _{FE}	160	250	400	-
$I_{\rm C}$ = 7 mA, $V_{\rm CE}$ = 3 V, pulse measured					

 $^{^{1}}T_{\mbox{\scriptsize S}}$ is measured on the collector lead at the soldering point to the pcb

 $^{^2\}mbox{For calculation}$ of $R_{\mbox{\scriptsize thJA}}$ please refer to Application Note Thermal Resistance



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified

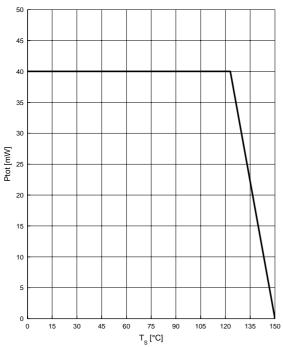
	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling	g)				
Transition frequency	f_{T}	-	39	-	GHz
$I_{\rm C} = 7 \text{ mA}, \ V_{\rm CE} = 3 \text{ V}, \ f = 1 \text{ GHz}$					
Collector-base capacitance	C _{cb}	-	0.04	0.08	pF
$V_{CB} = 3 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0,$					
emitter grounded					
Collector emitter capacitance	C_{ce}	-	0.15	-	
$V_{CE} = 3 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0,$					
base grounded					
Emitter-base capacitance	C _{eb}	-	0.18	-	
$V_{EB} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{CB} = 0$,					
collector grounded					
Noise figure	F				dB
$I_{C} = 3 \text{ mA}, V_{CE} = 3 \text{ V}, f = 1.8 \text{ GHz}, Z_{S} = Z_{Sopt}$		-	0.5	-	
$I_{C} = 3 \text{ mA}, V_{CE} = 3 \text{ V}, f = 6 \text{ GHz}, Z_{S} = Z_{Sopt}$		-	0.8	-	
Power gain, maximum stable ¹⁾	G _{ms}	-	25	-	dB
$I_{C} = 7 \text{ mA}, V_{CE} = 3 \text{ V}, Z_{S} = Z_{Sopt},$					
$Z_L = Z_{Lopt}$, $f = 1.8 \text{ GHz}$					
Power gain, maximum available ¹⁾	G _{ma}	-	18	-	dB
$I_{C} = 7 \text{ mA}, V_{CE} = 3 \text{ V}, Z_{S} = Z_{Sopt},$					
$Z_{L} = Z_{Lopt}$, $f = 6$ GHz					
Transducer gain	$ S_{21e} ^2$				dB
$I_{C} = 7 \text{ mA}, \ V_{CE} = 3 \text{ V}, Z_{S} = Z_{L} = 50 \ \Omega,$					
f = 1.8 GHz		-	21	-	
f = 6 GHz		-	14	-	

 $^{^{1}}G_{\text{ma}} = |S_{21e} / S_{12e}| \text{ (k-(k^2-1)}^{1/2}), \ G_{\text{ms}} = |S_{21e} / S_{12e}|$



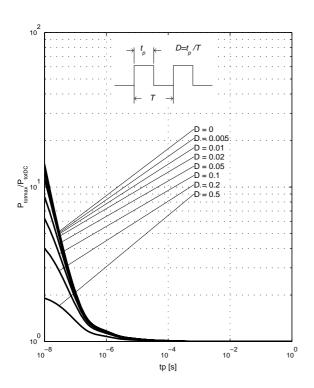
Total power dissipation $P_{tot} = f(T_S)$

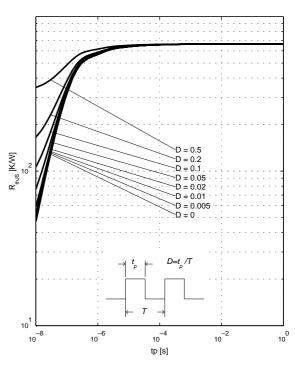
Permissible Puls Load $R_{thJS} = f(t_p)$



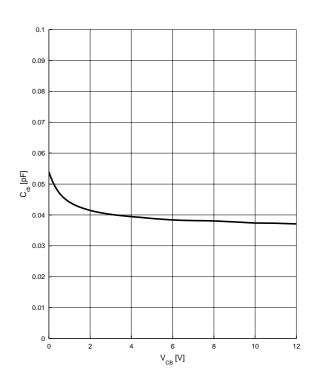


 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{p})$





Collector-base capacitance $C_{cb} = f (V_{CB})$ f = 1 MHz

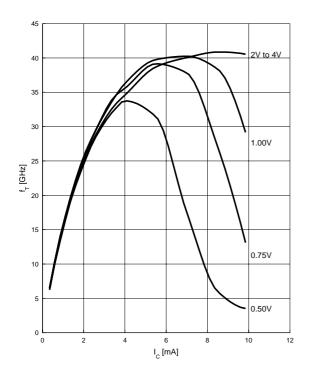


4



Transition frequency $f_T = f(I_C)$

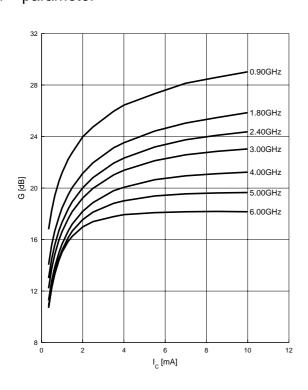
 V_{CE} = parameter, f = 1 GHz



Power gain G_{ma} , $G_{ms} = f(I_C)$

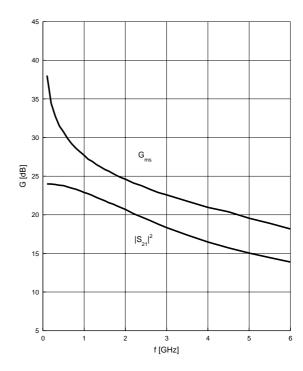
 $V_{CE} = 3 \text{ V}$

f = parameter



Power gain G_{ma} , $G_{ms} = f(f)$

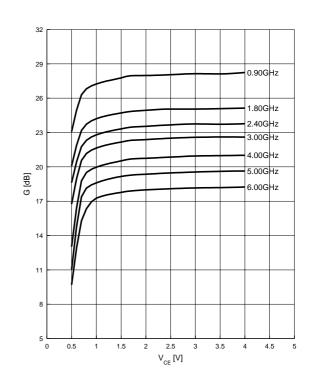
 $V_{CE} = 2 \text{ V}, I_{C} = 7 \text{ mA}$



Power gain G_{ma} , $G_{ms} = f(V_{CE})$

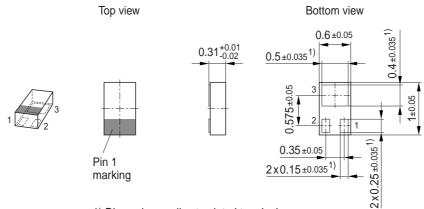
 $I_{\rm C} = 7 \, \rm mA$

f = parameter





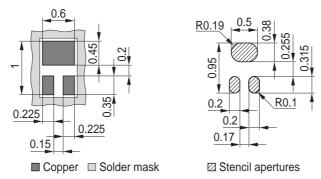
Package Outline



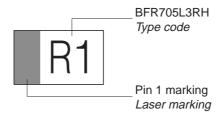
1) Dimension applies to plated terminal

Foot Print

For board assembly information please refer to Infineon website "Packages"

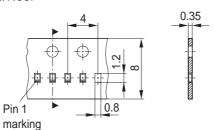


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



6



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7

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